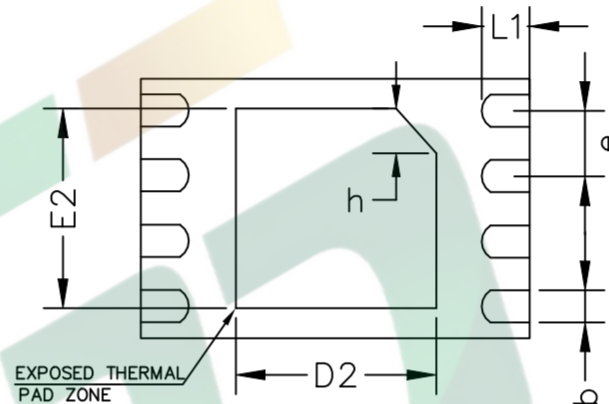
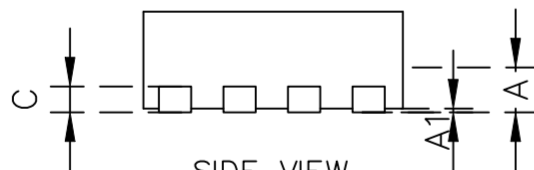


TOP VIEW



BOTTOM VIEW



SIDE VIEW

| SYMBOL | MIN    | NOM  | MAX  |
|--------|--------|------|------|
| A      | 0.7    | 0.75 | 0.8  |
| A1     | -      | 0.02 | 0.05 |
| b      | 0.23   | 0.25 | 0.28 |
| c      | 0.19   | 0.2  | 0.21 |
| D      | 2.9    | 3.0  | 3.1  |
| D2     | 1.55   | 1.6  | 1.65 |
| e      | 0.5BSC |      |      |
| E      | 1.9    | 2.0  | 2.1  |
| E2     | 1.45   | 1.5  | 1.55 |
| h      | 0.3    | 0.35 | 0.4  |
| L1     | 0.35   | 0.4  | 0.45 |

NOTES:  
 1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-229.  
 2. DIMENSION D DOES NOT INCLUDE MOLD FLASH  
 3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH  
 4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.



上海季丰电子科技有限公司

GIGA FORCE ELECTRONICS CO., Limited

|    |            |                |                                 |       |
|----|------------|----------------|---------------------------------|-------|
| 制图 | 王磊         | Title          | DFN8L (2X3X0.75) -P0.5 (CU&PPF) |       |
| 核准 | 何桂港        | POD No         | POD-SHJF-04                     |       |
| 日期 | 2022. 3. 6 | DIMENSIONS IN: | mm                              | Rev:A |